

### General Description

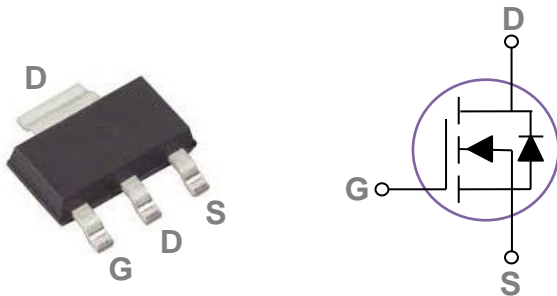
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
60V	75mΩ	5A

### Features

- 60V,5A, R<sub>DS(ON)</sub> = 75mΩ @ V<sub>GS</sub> = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### SOT223 Pin Configuration



### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	5	A
	Drain Current – Continuous (T <sub>A</sub> =70°C)	4	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	20	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	8	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	12.8	A
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> =25°C)	3.6	W
	Power Dissipation – Derate above 25°C	0.03	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient (t ≤ 10s)	---	35	°C/W
	Thermal Resistance Junction to ambient (Steady State)	---	70	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.05	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	---	60	75	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	---	70	90	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.8	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A	---	7	---	S

**Dynamic and switching Characteristics**

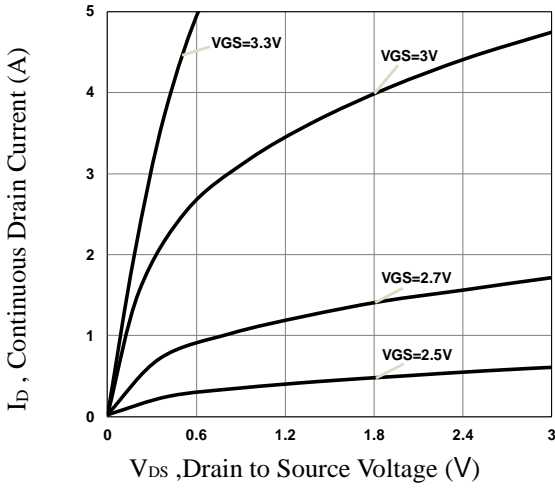
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =3A	---	4.6	8	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	0.4	3	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	2	4	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =3A	---	2.9	6	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	9.5	18	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	18.4	35	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	5.3	10	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, F=1MHz	---	360	540	pF
C <sub>oss</sub>	Output Capacitance		---	30	45	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	20	30	
R <sub>g</sub>	Gate resistance		V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	2	

**Drain-Source Diode Characteristics and Maximum Ratings**

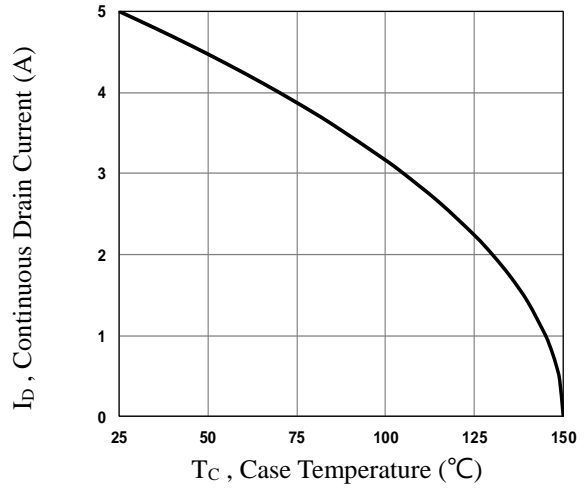
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	5	A
I <sub>SM</sub>	Pulsed Source Current		---	---	20	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>	V <sub>R</sub> =50V, I <sub>S</sub> =3A	---	25	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge <sup>2</sup>	di/dt=100A/μs, T <sub>J</sub> =25°C	---	15	---	nC

Note :

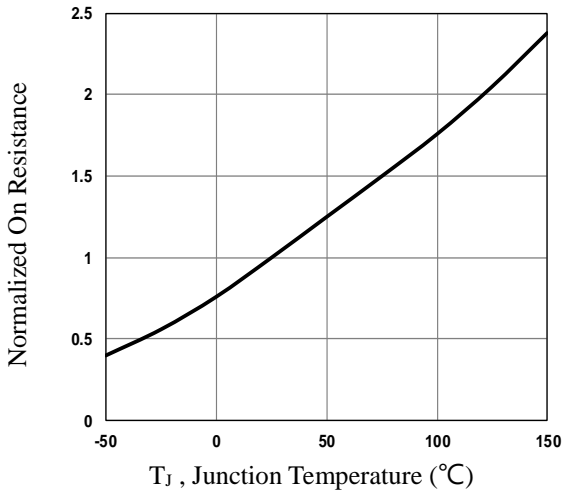
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=12.8A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



**Fig.1 Typical Output Characteristics**



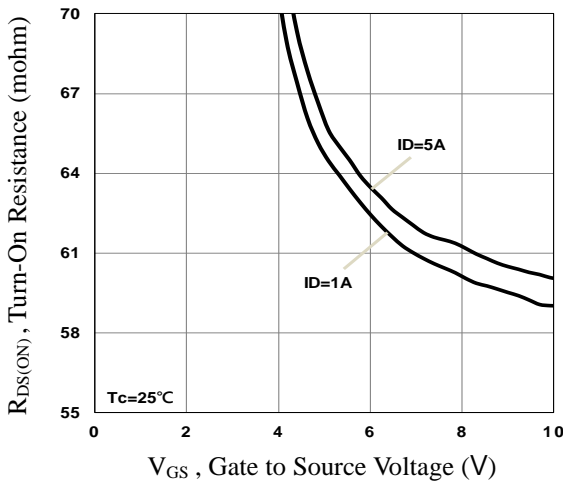
**Fig.2 Continuous Drain Current vs. T<sub>c</sub>**



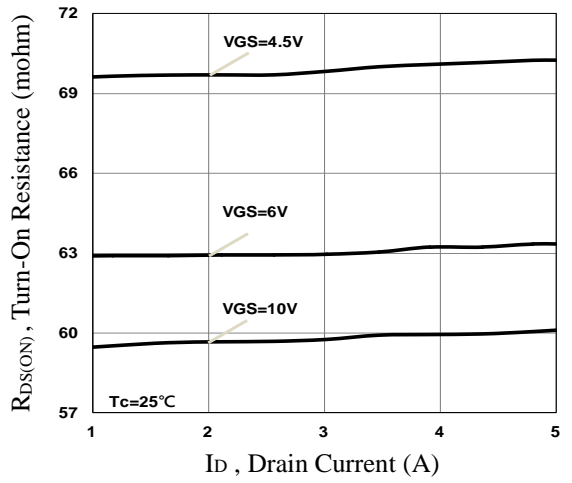
**Fig.3 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**



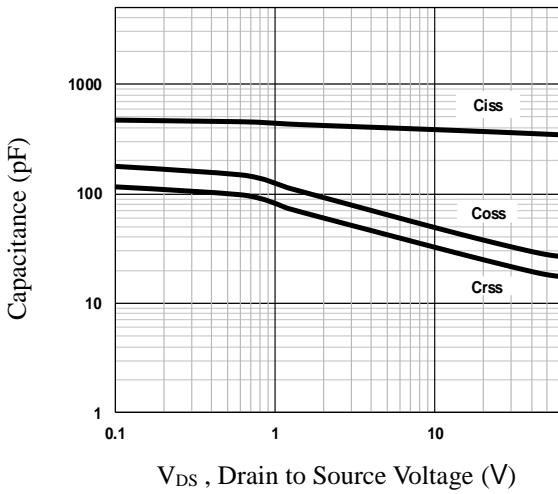
**Fig.4 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



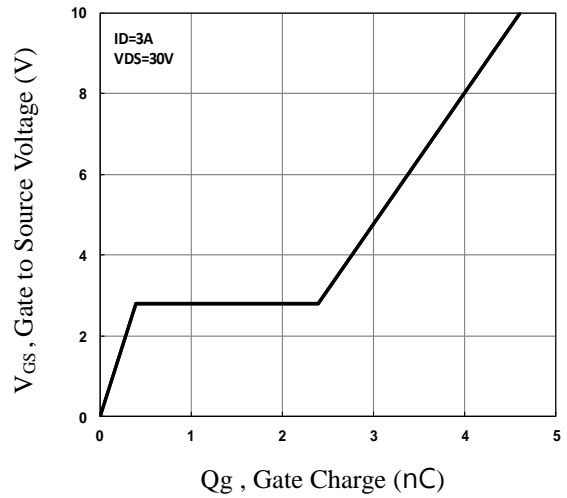
**Fig.5 Turn-On Resistance vs. V<sub>GS</sub>**



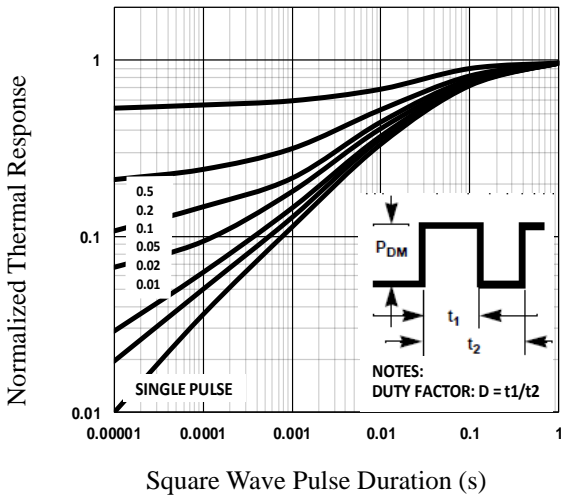
**Fig.6 Turn-On Resistance vs. I<sub>D</sub>**



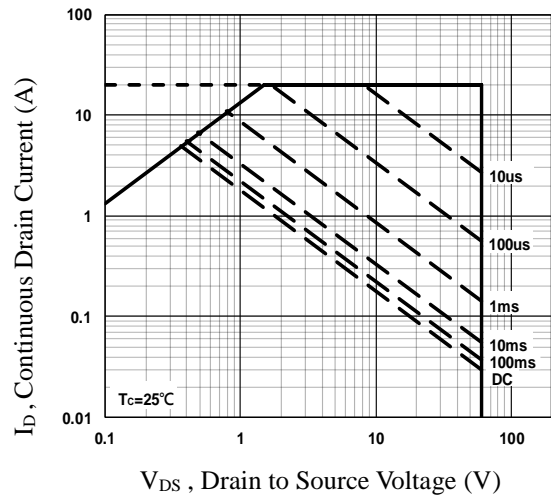
**Fig.7 Capacitance Characteristics**



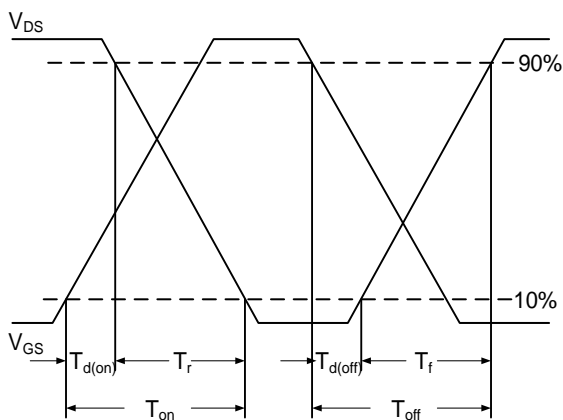
**Fig.8 Gate Charge Characteristics**



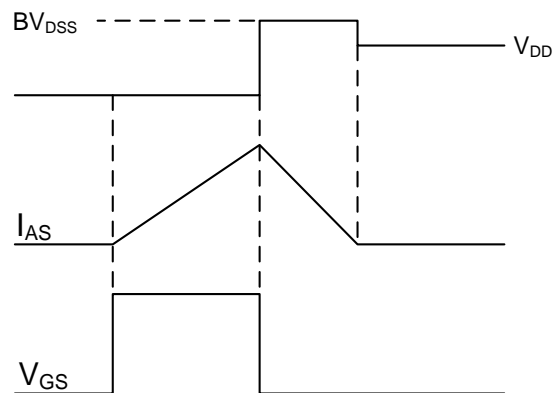
**Fig.9 Normalized Transient Impedance**



**Fig.10 Maximum Safe Operation Area**

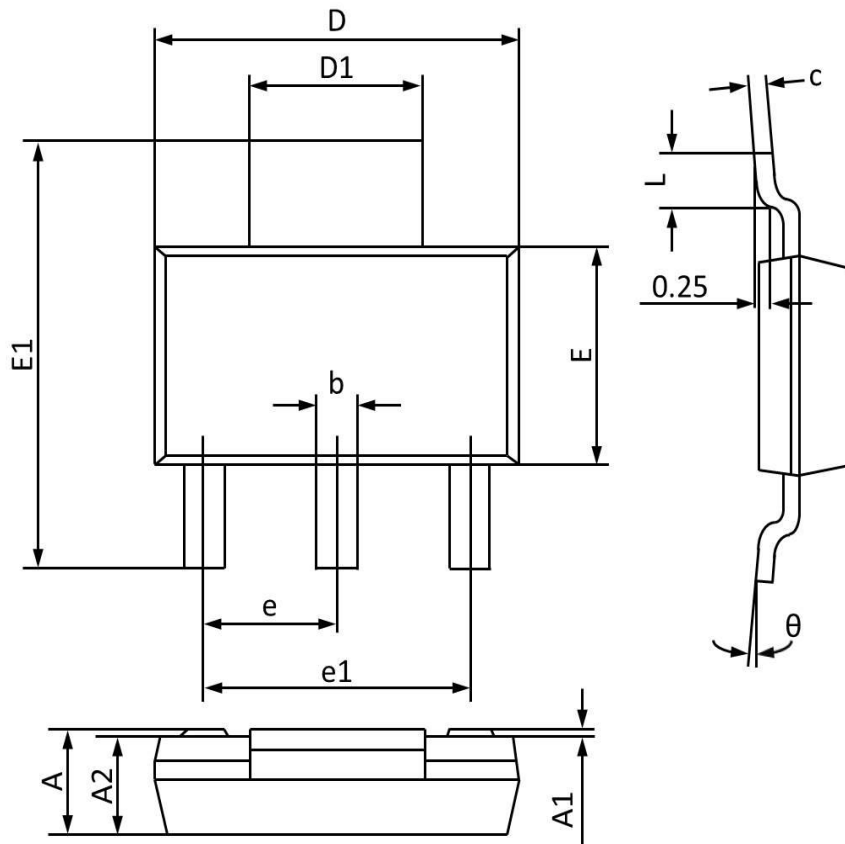


**Fig.11 Switching Time Waveform**



**Fig.12 EAS Waveform**

## SOT223 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.800	1.500	0.071	0.060
A1	0.120	0.000	0.005	0.000
A2	1.750	1.450	0.069	0.057
b	0.820	0.600	0.032	0.024
c	0.350	0.200	0.014	0.008
D	6.700	6.200	0.264	0.244
D1	3.100	2.900	0.122	0.114
E	3.700	3.300	0.146	0.130
E1	7.300	6.700	0.287	0.264
e	2.30(BSC)		0.091(BSC)	
e1	4.700	4.400	0.185	0.173
L	1.150	0.900	0.045	0.035
$\theta$	10°	0°	10°	0°